PATENT ASSIGNMENT

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SUBMISSION TYPE:	NEW ASSIGNMENT
NATURE OF CONVEYANCE:	ASSIGNMENT

CONVEYING PARTY DATA

Name	Execution Date
Lie-Yong Yang	04/13/2011
Sheng Chiang Hung	04/13/2011
Kian-Long Lim	04/13/2011

RECEIVING PARTY DATA

Name:	Taiwan Semiconductor Manufacturing Company, Ltd.
Street Address:	No. 8, Li-Hsin Road 6
City:	Hsin-Chu
State/Country:	TAIWAN
Postal Code:	300-77

PROPERTY NUMBERS Total: 1

Property Type	Number
Application Number:	13087016

OP $40.00 13087016

CORRESPONDENCE DATA

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NAME OF SUBMITTER:	Rachel L.I. Davis

Total Attachments: 3
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Docket No.: 2010-1311 / 24061.1717
Customer No.: 42717

ASSIGNMENT

WHEREAS, we,

(1) Lie-Yong Yang of 8, Li-Hsin Road 6, SBIP
Hsinchu 300-77, Taiwan, R.O.C.

(2) Sheng Chiang Hung of 6F-1, No. 60, Lyushuei Road
Hsinchu City 300, Taiwan, R.O.C.

(3) Kian-Long Lim of Room A, 9F, No. 20, Alley 53, Lane 2, Jinshan 11st St., East District
Hsinchu City 300, Taiwan, R.O.C.

(4) Ping-Wei Wang of 9F, No. 22, Lane 23, Jian-Zhong 1st Road
Hsin-Chu, Taiwan, R.O.C.

have invented certain improvements in

DIVOT ENGINEERING FOR ENHANCED DEVICE PERFORMANCE

for which we have executed an application for Letters Patent of the United States of America, filed on 04-14-2011 and assigned application number 13/087,016; and

WHEREAS, Taiwan Semiconductor Manufacturing Company, Ltd., ("TSMC"), No. 8, Li-Hsin Rd. 6, Science-Based Industrial Park Hsin-Chu, Taiwan 300-77, Republic of China. is desirous of obtaining the entire right, title, and interest in, to and under the said invention and the said application in the United States of America and in any and all countries foreign thereto;

NOW, THEREFORE, for good and valuable consideration, the receipt and sufficiency of which is hereby acknowledged, and other good and valuable consideration, we have sold, assigned, transferred and set over, and by these presents do hereby sell, assign, transfer and set over, unto the said TSMC, its successors, legal representatives, and assigns, the entire right, title, and interest in, to and under the said invention, and the said application, and all divisional, renewal, substitutional, and continuing applications thereof, and all Letters Patent of the United States of America which may be granted thereon and all reissues and extensions thereof, and all applications for Letters Patent which may be filed for said invention in any country or countries foreign to the United States of America, and all extensions, renewals, and reissues thereof, and all prior patents and patent applications from which a filing priority of the above-described patent application may be obtained, including the right to collect past damages; and we hereby authorize and request the Commissioner of Patents of the United States of America, and any official of any country or countries foreign to the United States of America, whose duty it is to issue patents on applications as aforesaid, to issue all Letters Patent for said invention to the said TSMC, its successors, legal representatives and assigns, in accordance with the terms of this instrument.

AND WE HEREBY covenant that we have full right to convey the entire interest herein assigned, and that we have not executed, and will not execute, any agreement in conflict herewith.

AND WE HEREBY further covenant and agree that we will communicate to said TSMC, its successors, legal representatives and assigns, any facts known to us respecting said invention, and testify in any legal proceedings, sign all lawful papers, execute all divisional, renewal, substitutional, continuing, and reissue applications, make all rightful declarations and/or oaths and generally do everything possible to aid the said TSMC, its successors, legal representatives and assigns, to obtain and enforce proper patent protection for said invention in all countries.

Inventor Name: Lie-Yong Yang

Residence Address: 8, Li-Hsin Road 6, SBIP
Hsinchu 300-77, Taiwan, R.O.C.

Dated: ✓ 13/04/2011

✓
Inventor Signature

Inventor Name: Sheng Chiang Hung

Residence Address: 6F-1, No. 60, Lyushuei Road
Hsinchu City 300, Taiwan, R.O.C.

Dated: ✓ 13/04/2011

✓ 洪聖強
Inventor Signature

Inventor Name: Kian-Long Lim

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Dated: ✓ 13/04/2011

✓
Inventor Signature

Inventor Name: Ping-Wei Wang

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Dated: ✓ 13/04/2011

✓ Ping Wei Wang
Inventor Signature
